Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN195101 **Date:** December 17, 2019

Subject: Qualification of Greatek Electronics as an Additional Assembly Site for Select 8-Lead SOIC Products

To: PCN Coordinator PCN Coordinator
FUTURE
PCN.System@Future.ca

Change Type: Major

Description of Change:
Cypress announces the qualification of Greatek Electronics Inc., (No.136, Gon-Yi Rd. Zhunan Township, Miaoli County 350 Taiwan, R.O.C.) as a new assembly site for select 8-Lead SOIC 208mils (5.28x5.28x2.16mm) and 150mils (3.90x4.90x1.75mm) products. Greatek Electronics is a world-class assembly facility, qualified to build standard and automotive grade products consistent with AEC-Q100/AEC-Q006 standards.

The 8-Lead SOIC Pb-Free (5.28x5.28mm, 208mils body) package is assembled at Greatek Electronics using the following bill of materials:

Material	GREATEK Bill of Materials	ZKT Bill of Materials
Mold Compound	SUMITOMO G700SLA	Samsung SG8300HKT/SG8500HKT
Leadfinish	Jau Janq Matte Sn	Yunan, Matte Sn
Die Attach Material	Hitachi-4900GC	Yizbond 8511
Bond Wire	Nippon 0.8mil PdCuAu	Nippon 0.8mil PdCuAu

The 8-Lead SOIC Pb-Free (3.90x4.90mm, 150mils body) package is assembled at Greatek Electronics using the following bill of materials:

Material	GREATEK Bill of Materials	ZKT Bill of Materials
Mold Compound	SUMITOMO G700HA	Samsung SG8300HKT
Leadfinish	Jau Janq Matte Sn	Yunan, Matte Sn
Die Attach Material	Hitachi-4900GC	Yizbond 8511
Bond Wire	MKE 0.9mil Au	Tanaka 0.9mil Au

Benefit of Change:
Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide

the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Part Numbers Affected: 100
See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:
This assembly site has been qualified through a series of tests documented in Qualification Test Plans QTP#191602 and QTP#191508. These qualification reports can be found as attachments to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:
Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated Greatek Electronics sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:
Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of Commercial, Industrial and Automotive non-PPAP part numbers in the attached file will be assembled at Greatek Electronics or other approved assembly sites.

For Automotive PPAP part numbers this change will be effective upon customer approval.

Anticipated Impact:
Products assembled at the new site are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,
Cypress PCN Administration

Cypress Semiconductor
Automotive Reliability Qualification Report

AEC-Q100 Automotive Qualification Test Plan Report for

S6BT112, 180nm, Grade-1 -40 to 125℃

Contents:

Q100 Qualification Test Plan

Automotive Grade Level = 1 **MSL = 3**

Supplier Name:	CYPRESS		**General Specification:**	AEC-Q100 Rev. H	
Supplier Code:			**Supplier Wafer Fabrication:**	TOWERJAZZ PANASONIC SEMICONDUCTOR	
Supplier Part Number:	S6BT112		**Supplier Wafer Test:**	TERAPROBE	
Supplier Contact:			**Supplier Assembly Site:**	GREATEK	
Supplier Family Type:	SOP8 (SOA008)		**Supplier Final Test Site:**	J-DEVICES FUKUOKA	
Device Description:	ASSP CXPI Transceiver IC for Automotive Network		**Supplier Reliability Signature:**		
PPAP Submission Date:			**Customer Test ID:**		
Reason for Qualification:	ASSEMBLY SITE QUALIFICATION (QTP#191508)		**Customer Part Number:**		
Prepared by Signature:	KUMI	Date: 12-Dec.-19	**Customer Approval Signature:**		Date:

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
TEST GROUP A – ACCELERATED ENVIRONMENT STRESS TESTS								
PC	A1	JESD22 A113 J-STD-020	Preconditioning: (Test @ Rm) SMD only; Moisture Preconditioning for THB/HAST, AC/UHST, TC, & PTC; Peak Reflow Temp = 260℃ -0/+5℃	Min. MSL = 3			MSL = 3	Before A2, A3, A4,
THB or HAST	A2	JESD22 A101 JESD22 A110	Highly Accelerated Stress Test: (Test @ Rm/Hot/) 110℃/85%RH, 264hrs	3	77	231	0 of 231	
AC or UHST or TH	A3	JESD22 A102 JESD22 A118 or JESD22-A101	Unbiased Highly Accelerated Stress Test: (Test @ Rm) 130℃/85%RH, 96hrs	3	77	231	0 of 231	
TC	A4	JESD22 A104	Temperature Cycle: (Test @ Hot) -65℃ to150℃, 500 Cycles	3	77	231	0 of 231	
PTC	A5	JESD22 A105	Power Temperature Cycle: (Test @ Rm/Hot) -40℃ to125℃, 500 Cycles	-	-	-	-	N/A

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
HTSL	A6	JESD22 A103	High Temperature Storage Life: (Test @ Rm/Hot) 150℃, 1000 Hrs	3	45	135	0 of 135	

TEST GROUP B – ACCELERATED LIFETIME SIMULATION TESTS

HTOL	B1	JESD22 A108	High Temp Operating Life: (Test @ Rm/Cold/Hot) 125℃, 1000 Hrs	3	77	231	0 of 231	
ELFR	B2	AEC-Q100-008	Early Life Failure Rate: (Test @ Rm/Hot) 125℃, 48 Hrs	3	800	2400	0 of 2400	
EDR	B3	AEC-Q100-005	NVM Endurance & Data Retention Test: (Test @ Rm/Hot) a. 125℃, 100K Cycles + 150℃ Bake, b. 125℃, 100K Cycles + 125℃ HTOL, c. 25℃, 100K Cycles + 25℃ Bake	-	-	-	-	N/A

TEST GROUP C – PACKAGE ASSEMBLY INTEGRITY TESTS

WBS	C1	AEC-Q100-001 AEC-Q003	Wire Bond Shear Test: (Cpk > 1.67)	30 bonds	5 parts Min.	30 bonds	Cpk > 1.67	
WBP	C2	Mil-STD-883, Method 2011 AEC-Q003	Wire Bond Pull: (Cpk > 1.67); Each bonder used	30 bonds	5 parts Min.	30 bonds	Cpk > 1.67	
SD	C3	JESD22 B102 JSTD-002D	Solderability: (>95% coverage) 8hr steam aging prior to testing	1	15	15	0 of 20	
PD	C4	JESD22 B100, JESD22 B108 AEC-Q003	Physical Dimensions: (Cpk > 1.67)	3	10	30	Cpk > 1.67	
SBS	C5	AEC-Q100-010 AEC-Q003	Solder Ball Shear: (Cpk > 1.67); 5 balls from min. of 10 devices	-	-	-	-	N/A
LI	C6	JESD22 B105	Lead Integrity: (No lead cracking or breaking); Through-hole only; 10 leads from each of 5 devices	-	-	-	-	N/A

TEST GROUP D – DIE FABRICATION RELIABILITY TESTS

EM	D1	JESD61	Electromigration: 110℃	-	-	-	-	N/A
TDDB	D2	JESD35	Time Dependant Dielectric Breakdown: 125℃	-	-	-	-	N/A

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
HCI	D3	JESD60 & 28	Hot Carrier Injection: 125℃, -40℃	-	-	-	-	N/A
NBTI	D4	JESD90	Negative Bias Temperature Instability: 125℃	-	-	-	-	N/A
SM	D5	JESD61, 87, & 202	Stress Migration: Ta = 200℃	-	-	-	-	N/A

TEST GROUP E- ELECTRICAL VERIFICATION

TEST	E1	User/Supplier Specification	Pre and Post Stress Electrical Test:	All	All	All	All	Performed for all qualification units
HBM	E2	AEC-Q100-002	Electrostatic Discharge, Human Body Model: (Test @ Rm/Hot); (2KV HBM / Class 2 or better)	1	3	3	-	N/A
CDM	E3	AEC-Q100-011	Electrostatic Discharge, Charged Device Model: (Test @ Rm/Hot); (750V corner leads, 500V all other leads / Class C4B or better)	1	3	3	0 of 18	
LU	E4	AEC-Q100-004	Latch-Up: (Test @ Rm/Hot) 125℃, +/- 100mA	1	6	6	-	N/A
ED	E5	AEC-Q100-009 AEC-Q003	Electrical Distributions: (Test @ Rm/Hot/Cold) (where applicable, Cpk >1.67)	3	30	90	Cpk > 1.67	
FG	E6	AEC-Q100-007	Fault Grading:	-	-	-	-	N/A
CHAR	E7	AEC-Q003	Characterization: (Test @ Rm/Hot/Cold)	-	-	-	-	N/A
EMC	E9	SAE J1752/3	Electromagnetic Compatibility (Radiated Emissions)	1	1	1	-	N/A
SC	E10	AEC Q100-012	Short Circuit Characterization	3	10	30	-	N/A
SER	E11	JESD89-1 JESD89-2 JESD89-3	Soft Error Rate	-	-	-	-	N/A
LF	E12	AEC-Q005	Lead (Pb) Free: (see AEC-Q005)	-	-	-	Pass	

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
TEST GROUP F – DEFECT SCREENING TESTS								
PAT	F1	AEC-Q001	Process Average Testing: (see AEC-Q001)	All	All	All	-	N/A
SBA	F2	AEC-Q002	Statistical Bin/Yield Analysis: (see AEC-Q002)	All	All	All	-	N/A
TEST GROUP G – CAVITY PACKAGE INTEGRITY TESTS (for Ceramic Package testing only)								
MS	G1	JESD22 B104	Mechanical Shock: (Test @ Rm)	1	15	15	of	N/A
VFV	G2	JESD22 B103	Variable Frequency Vibration: (Test @ Rm)	1	15	15	of	N/A
CA	G3	MIL-STD-883 Method 2001	Constant Acceleration: (Test @ Rm)	1	15	15	of	N/A
GFL	G4	MIL-STD-883 Method 1014	Gross and Fine Leak:	1	15	15	of	N/A
DROP	G5	----------	Drop Test: (Test @ Rm) MEMS cavity parts only. Drop part on each of 6 axes once from a height of 1.2m onto a concrete surface.	1	5	5	of	N/A
LT	G6	MIL-STD-883 Method 2004	Lid Torque:	1	5	5	of	N/A
DS	G7	MIL-STD-883 Method 2019	Die Shear:	1	5	5	of	N/A
IWV	G8	MIL-STD-883 Method 1018	Internal Water Vapor:	1	5	5	of	N/A

Document History Page

Document Title: S6BT112 Product Greatek Assembly Site AEC-Q100 Qualification Report
Document Number: 002-29288

Rev.	ECN No.	Orig. of Change	Description of Change
**	6750862	KUMI	Initial release

Cypress Semiconductor
Automotive Reliability Qualification Report

AEC-Q100 Automotive Qualification Test Plan Report for

Qualification of Greatek As Alternate Assembly Location for SOIC008, Grade 3 -40 to 85C

Contents:

Q100 Qualification Test Plan

Automotive Grade Level = 3 -40 to +85C **MSL = 3**

Supplier Name:	CYPRESS		**General Specification:**	AEC-Q100 Rev. H	
Supplier Code:			**Supplier Wafer Fabrication:**	FAB25 (Austin), WXIC (China)	
Supplier Part Number:			**Supplier Wafer Test:**	TEST25 (Austin)	
Supplier Contact:			**Supplier Assembly Site:**	GreaTek (Taiwan)	
Supplier Family Type:	SOC008		**Supplier Final Test Site:**	CYPRESS BKK (Thailand)	
Device Description:			**Supplier Reliability Signature:**		
PPAP Submission Date:			**Customer Test ID:**		
Reason for Qualification:	New Assembly Location Qualification		**Customer Part Number:**		
Prepared by Signature:	EKNG	Date: 12-11-19	**Customer Approval Signature:**		Date:

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
TEST GROUP A – ACCELERATED ENVIRONMENT STRESS TESTS								
PC	A1	JESD22 A113 J-STD-020	Preconditioning: (Test @ Rm) SMD only; Moisture Preconditioning for THB/HAST, AC/UHST, TC, & PTC; Peak Reflow Temp = 260C,+5/-0	Min. MSL = 3			MSL = 3	Spansion RQ Results SOC008 = (9 Lots, 2259 Units, 0 Fails), 3X Reflow
THB or HAST	A2	JESD22 A101 JESD22 A110	Temperature Humidity Bias: (Test @ Rm/Hot) Highly Accelerated Stress Test: (Test @ Rm/Hot/) 130C/85%RH, 3.0V, 96Hrs, 192hrs	3	77	231	0 of 693	a. Results SOC008 = (9 Lots, 693 Units, 0 Fails)
AC or UHST or TH	A3	JESD22 A102 JESD22 A118 or JESD22-A101	Autoclave: (Test @ Rm) Unbiased Highly Accelerated Stress Test: (Test @ Rm) Temperature Humidity without Bias: (Test @ Rm) 130C/85%RH, 96Hrs	3	77	231	0 of 693	a. Results SOC008 = (9 Lots, 693 Units, 0 Fails)
TC	A4	JESD22 A104	Temperature Cycle: (Test @ Hot) -65C to 150C, 500, 1000 Cycles	3	77	231	0 of 693	a. Results SOC008 = (9 Lots, 693 Units, 0 Fails)
PTC	A5	JESD22 A105	Power Temperature Cycle: (Test @ Rm/Hot)	1	45	45	of	N/A. CYPRESS performs normal Temperature Cycling instead of PTC.
HTSL	A6	JESD22 A103	High Temperature Storage Life: (Test @ Rm/Hot) 150C, 1000, 2000 Hrs	1	45	45	0 of 450	a. Results SOC008 = (9 Lot, 450 Units, 0 Fails)

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
TEST GROUP B – ACCELERATED LIFETIME SIMULATION TESTS								
HTOL	B1	JESD22 A108	High Temp Operating Life: (Test @ Rm/Cold/Hot) 125C, 3.6V, 1000 Hrs.	3	77	231	0 of 693	a. Results SOC008 = (9 Lot, 693 Units, 0 Fails)
ELFR	B2	AEC-Q100-008	Early Life Failure Rate: (Test @ Rm/Hot) 48 Hrs. @ 125C, 3.6V	3	800	2400	0 of 4800	Result SOC008 = (various Lots, 4800 Units, 0 Fails)
EDR	B3	AEC-Q100-005	NVM Endurance & Data Retention Test: (Test @ Rm/Hot) 85C, 3.6V, 10K Cycles	3	77	231	0 of 231	Results SOC008 = (Various Lot, 231 Units, 0 Fails)
TEST GROUP C – PACKAGE ASSEMBLY INTEGRITY TESTS								
WBS	C1	AEC-Q100-001 AEC-Q003	Wire Bond Shear Test: (Cpk > 1.67)	30 bonds	5 parts Min.	bonds	0 of 150	Results SOC008 = (30 Bonds/ 0 Fails)
WBP	C2	Mil-STD-883, Method 2011 AEC-Q003	Wire Bond Pull: (Cpk > 1.67); Each bonder used	30 bonds	5 parts Min.	bonds	0 of 150	Results SOC008 = (30 Bonds/ 0 Fails)
SD	C3	JESD22 B102 JSTD-002D	Solderability: (>95% coverage) 8hr steam aging prior to testing	1	15	15	0 of 45	a. Results SOC008 = (3 Lots, 45 Units, 0 Fails)
PD	C4	JESD22 B100, JESD22 B108 AEC-Q003	Physical Dimensions: (Cpk > 1.67)	3	10	30	0 of 30	a. Results SOC008 = (1 Lot, 30 Units, 0 Fails)
SBS	C5	AEC-Q100-010 AEC-Q003	Solder Ball Shear: (Cpk > 1.67); 5 balls from min. of 10 devices	3	50 balls	150	of	N/A
LI	C6	JESD22 B105	Lead Integrity: (No lead cracking or breaking); Through-hole only; 10 leads from each of 5 devices	1	50 leads	50	0 of 50	a. Results SOC008 = (3 Lot, 50 Leads /Lot/ 0 Fails)
TEST GROUP D – DIE FABRICATION RELIABILITY TESTS								
EM	D1	JESD61	Electromigration: Constant current 0.8MA/cm2 and 10MA/cm2 at 225C and 250C	-	-	-		Data Available TQ Generic Data Results = Pass 100khr operating equivalent
TDDB	D2	JESD35	Time Dependant Dielectric Breakdown: Constant voltage 6-9MV.cm at 130C	-	-	-		Data Available TQ Generic Data Results = Pass 100khr operating equivalent
HCI	D3	JESD60 & 28	Hot Carrier Injection: Vg at Isubmax with 3 Vds conditions	-	-	-		Data Available TQ Generic Data Results = Pass 100khr operating equivalent
NBTI	D4	JESD90	Negative Bias Temperature Instability: -4.8V/-5.2V/-5.6V at 150C and 200C	-	-	-		Data Available TQ Generic Data Results = Pass 100khr operating equivalent

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
SM	D5	JESD61, 87, & 202	Stress Migration: Ta = 200C	-	-	-		Data Available TQ Generic Data Results = Pass 100khr operating equivalent

TEST GROUP E- ELECTRICAL VERIFICATION

TEST	E1	User/Supplier Specification	Pre and Post Stress Electrical Test:	All	All	All	of	Performed on all qualification units.
HBM	E2	AEC-Q100-002	Electrostatic Discharge, Human Body Model: (Test @ Rm/Hot); (2KV HBM / Class 2 or better) HBM (100pF, 1,500 ohms)	1	42	42	0 of 60 ESD Level = H2	Results SOC008 = (1 Lot, 60 Units, 0 Fails) Pass +/-2.0kV HBM.
CDM	E3	AEC-Q100-011	Electrostatic Discharge, Charged Device Model: (Test @ Rm/Hot); (750V corner leads, 500V all other leads / Class C4B or better)	1	12	12	0 of 54 ESD Level = C4	Results SOC008 = (3 Lots, 54 Units, 0 Fails). Pass 1kV CDM.
LU	E4	AEC-Q100-004	Latch-Up: (Test @ Rm/Hot) 125C +/- 100mA, Class II	1	6	6	0 of 6	Results SOC008 = (1 Lot, 6 Units, 0 Fails)
ED	E5	AEC-Q100-009 AEC-Q003	Electrical Distributions: (Test @ Rm/Hot/Cold) (where applicable, Cpk >1.67) (Test at 25C, 85C, &-40C Pre- and Post-)	3	30	90	0 of 90	Refer to QDB of characterization data
FG	E6	AEC-Q100-007	Fault Grading:	-	-	-	Fault Grade	N/A. But CYPRESS screens out the failures through internal test mode and 100% tested to sort and class tests.
CHAR	E7	AEC-Q003	Characterization: (Test @ Rm/Hot/Cold) (at 25C, 85C & -40C)	-	-	-	Requested Data	Pls refer to Device Characterization Data in QDB
EMC	E9	SAE J1752/3	Electromagnetic Compatibility (Radiated Emissions) Magnetic and Electric Field	1	1	1	1	Data will be provided upon customer request.
SC	E10	AEC Q100-012	Short Circuit Characterization	3	10	30		Applicable for smart power device only per AEC Q100.
SER	E11	JESD89-1 JESD89-2 JESD89-3	Soft Error Rate	1	3	3		N/A. But, Spansion performed some accelerated neutron irradiation tests on our product. Refer separate document for more information
LF	E12	AEC-Q005	Lead (Pb) Free: (see AEC-Q005)	-	-	-	1	Pass.

TEST GROUP F – DEFECT SCREENING TESTS

Test	#	Reference	Test Conditions	Lots	S.S.	Total	Results Lot/Pass/Fail	Comments: (N/A =Not Applicable)
PAT	F1	AEC-Q001	Process Average Testing: (see AEC-Q001)	All	All	All	Reject units outside Avg.	Spansion incorporates the principle of PAT methodology
SBA	F2	AEC-Q002	Statistical Bin/Yield Analysis: (see AEC-Q002)	All	All	All	Reject units outside criteria	Spansion incorporates the principle of SBA methodology

TEST GROUP G – CAVITY PACKAGE INTEGRITY TESTS (for Ceramic Package testing only)

MS	G1	JESD22 B104	Mechanical Shock: (Test @ Rm)	1	15	15	of	N/A. Applicable for ceramic package only
VFV	G2	JESD22 B103	Variable Frequency Vibration: (Test @ Rm)	1	15	15	of	N/A. Applicable for ceramic package only
CA	G3	MIL-STD-883 Method 2001	Constant Acceleration: (Test @ Rm)	1	15	15	of	N/A. Applicable for ceramic package only
GFL	G4	MIL-STD-883 Method 1014	Gross and Fine Leak:	1	15	15	of	N/A. Applicable for ceramic package only
DROP	G5	----------	Drop Test: (Test @ Rm) MEMS cavity parts only. Drop part on each of 6 axes once from a height of 1.2m onto a concrete surface.	1	5	5	of	N/A. Applicable for ceramic package only
LT	G6	MIL-STD-883 Method 2004	Lid Torque:	1	5	5	of	N/A. Applicable for ceramic package only
DS	G7	MIL-STD-883 Method 2019	Die Shear:	1	5	5	of	N/A. Applicable for ceramic package only
IWV	G8	MIL-STD-883 Method 1018	Internal Water Vapor:	1	5	5	of	N/A. Applicable for ceramic package only

Document History Page

Document Title: AEC-Q100 Automotive Qualification Test Plan Report for Qualification of Greatek As Alternate Assembly Location for SOIC008, Grade 3 -40 to 85C

Document Number: 002-29234

Rev.	ECN No.	Orig. of Change	Description of Change
**	6749805	EKNG	Qualification of Greatek As Alternate Assembly Location for SOIC008, Grade 3 -40 to 85C

Item	Marketing Part Number	Sample Order Part Number
1	00002337541	S25FL032P0XMFA010-004
2	0791076249RQA00	S25FL127SABMFB100-004
3	10324-08810	S25FL064LABMFB010-004
4	28294110 A	S25FL032P0XMFB010-004
5	28417804 A	S25FL127SABMFB100-004
6	28431985 A	S25FL127SABMFA100-004
7	315-1820-000	S25FL127SABMFB100-004
8	51-40300Z01	S25FS128SAGMFB100-004
9	520966230646	S25FL032P0XMFA010-004
10	520966231016	S25FL032P0XMFA010-004
11	520966231926	S25FL064LABMFB010-004
12	793.846-00	S25FL064LABMFM010-004
13	794.155-00	S25FL064LABMFB010-004
14	8 611 200 150	S25FL032P0XMFB010-004
15	8 611 200 897	S25FL032P0XMFA010-004
16	A2C00051729 A	S25FL032P0XMFB010-004
17	A2C01952000 A	S25FL032P0XMFB010-004
18	A2C0195200000 A	S25FL032P0XMFB010-004
19	A2C02419300 A	S25FL064LABMFB010-004
20	A2C0241930000 A	S25FL064LABMFB010-004
21	A2C02457200 A	S25FS128SAGMFB100-004
22	A2C03931100	S25FL064LABMFM010-004
23	C08-0585-0001-0	S25FL127SABMFB100-004
24	C3FBNY000291	S25FL032P0XMFA010-004
25	C3FBPY000362	S25FL064LABMFB010-004
26	C3FBQY000134	S25FL127SABMFA100-004
27	C3FS00000031	S25FL064LABMFM010-004
28	CISH-IC1037808-000	S25FL064LABMFM010-004
29	EAN64027701	S25FL127SABMFB100-004
30	EAN64668101	S25FL064LABMFM010-004
31	EAN65106801	S25FL064LABMFB010-004
32	J005-S2532-001	S25FL032P0XMFA010-004
33	P770022CF6C000	S25FL032P0XMFA010-004
34	P770022C-F6C000	S25FL032P0XMFA010-004
35	P770029DF70000	S25FL064LABMFM010-004
36	P770029D-F70000	S25FL064LABMFM010-004
37	RENMEM-00001	S25FL064LABMFM010-004
38	RENMEM-00003	S25FL064LABMFM010-004
39	SRC100242278	S6BT112A02SSBB002-004
40	S25FL032P0XMFA010	S25FL032P0XMFA010-004
41	S25FL032P0XMFA013	S25FL032P0XMFA010-004
42	S25FL032P0XMFB013	S25FL032P0XMFB010-004
43	S25FL064LABMFA010	S25FL064LABMFA010-004
44	S25FL064LABMFA010CL	S25FL064LABMFA010-004
45	S25FL064LABMFA011	S25FL064LABMFA010-004
46	S25FL064LABMFA013	S25FL064LABMFA010-004
47	S25FL064LABMFB010	S25FL064LABMFB010-004
48	S25FL064LABMFB011	S25FL064LABMFB010-004

49	S25FL064LABMFB013	S25FL064LABMFB010-004
50	S25FL064LABMFI010	S25FL064LABMFI010-004
51	S25FL064LABMFI011	S25FL064LABMFI010-004
52	S25FL064LABMFI013	S25FL064LABMFI010-004
53	S25FL064LABMFM010	S25FL064LABMFM010-004
54	S25FL064LABMFM011	S25FL064LABMFM010-004
55	S25FL064LABMFM013	S25FL064LABMFM010-004
56	S25FL064LABMFN010	S25FL064LABMFN010-004
57	S25FL064LABMFN013	S25FL064LABMFN010-004
58	S25FL064LABMFV010	S25FL064LABMFV010-004
59	S25FL064LABMFV011	S25FL064LABMFV010-004
60	S25FL064LABMFV013	S25FL064LABMFV010-004
61	S25FL127SABMFB100	S25FL127SABMFB100-004
62	S25FL127SABMFB101	S25FL127SABMFB100-004
63	S25FL127SABMFB103	S25FL127SABMFB100-004
64	S25FL127SABMFI100	S25FL127SABMFI100-004
65	S25FL127SABMFI101	S25FL127SABMFI100-004
66	S25FL127SABMFI103	S25FL127SABMFI100-004
67	S25FL127SABMFV100	S25FL127SABMFV100-004
68	S25FL127SABMFV101	S25FL127SABMFV100-004
69	S25FL127SABMFV103	S25FL127SABMFV100-004
70	S25FL128LAGMFA010	S25FL128LAGMFA010-004
71	S25FL128LAGMFA013	S25FL128LAGMFA010-004
72	S25FL128LAGMFB010	S25FL128LAGMFB010-004
73	S25FL128LAGMFB013	S25FL128LAGMFB010-004
74	S25FL128LAGMFI010	S25FL128LAGMFI010-004
75	S25FL128LAGMFI013	S25FL128LAGMFI010-004
76	S25FL128LAGMFM010	S25FL128LAGMFM010-004
77	S25FL128LAGMFM013	S25FL128LAGMFM010-004
78	S25FL128LAGMFV010	S25FL128LAGMFV010-004
79	S25FL128LAGMFV013	S25FL128LAGMFV010-004
80	S25FS128SAGMFB100	S25FS128SAGMFB100-004
81	S25FS128SAGMFB101	S25FS128SAGMFB100-004
82	S25FS128SAGMFB103	S25FS128SAGMFB100-004
83	S25FS128SAGMFI100	S25FS128SAGMFI100-004
84	S25FS128SAGMFI101	S25FS128SAGMFI100-004
85	S25FS128SAGMFI103	S25FS128SAGMFI100-004
86	S25FS128SAGMFV100	S25FS128SAGMFV100-004
87	S25FS128SAGMFV101	S25FS128SAGMFV100-004
88	S25FS128SAGMFV103	S25FS128SAGMFV100-004
89	S25FS128SDSMFI1D0	S25FS128SDSMFI1D0-004
90	S25FS128SDSMFI1D1	S25FS128SDSMFI1D0-004
91	S25FS128SDSMFI1D3	S25FS128SDSMFI1D0-004
92	S6BT112A01SSBB002	S6BT112A01SSBB002-004
93	S6BT112A01SSBB202	S6BT112A01SSBB002-004
94	S6BT112A02SSBB002	S6BT112A01SSBB002-004
95	S6BT112A02SSBB202	S6BT112A01SSBB002-004
96	S99-50363 P	S25FL032P0XMFA010-004
97	S99FL127S0013 P	S25FL127SABMFA100-004

98	S99FL127S0013 P	S25FL127SABMFA100-004
99	S99FL127SABMFI101	S99FL127SABMFI100-004
100	SE002718	S25FL064LABMFM010-004

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